



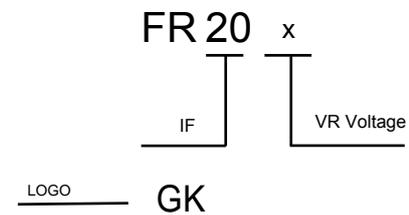
## FEATURES

- \* Low forward voltage drop
- \* High current capability
- \* High reliability
- \* High surge current capability

## MECHANICAL DATA

- \* Case: Molded plastic
- \* Epoxy: UL 94V-0 rate flame retardant
- \* Lead: Axial leads, solderable per MIL-STD-202, method 208 guaranteed
- \* Polarity: Color band denotes cathode end
- \* Mounting position: Any

VOLTAGE RANGE  
50 to 1000 Volts  
CURRENT  
2.0 Ampere



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.  
Single phase half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

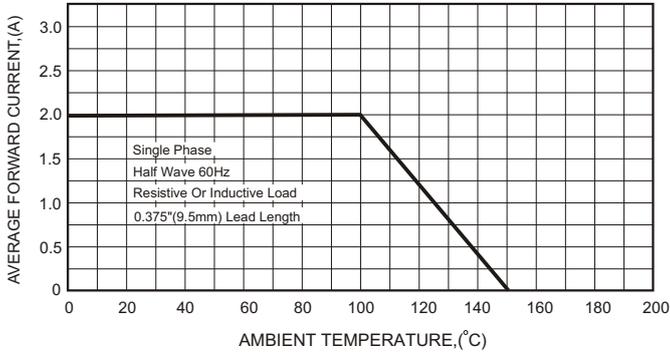
TYPE NUMBER	FR201	FR202	FR203	FR204	FR205	FR206	FR207	UNITS
Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	2.0							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	60							A
Maximum Instantaneous Forward Voltage at 2.0A	1.3							V
Maximum DC Reverse Current Ta=25°C	5.0							μA
at Rated DC Blocking Voltage Ta=100°C	100							μA
Maximum Reverse Recovery Time (Note 1)	150			250		500		nS
Typical Junction Capacitance (Note 2)	40							pF
Operating and Storage Temperature Range Tj, Tstg	-65 — +150							°C

### NOTES:

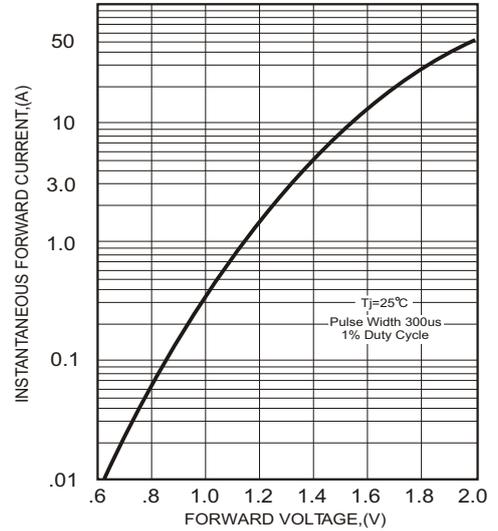
1. Reverse Recovery Time test condition: IF=0.5A, IR=1.0A, IRR=0.25A
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

**RATING AND CHARACTERISTIC CURVES**

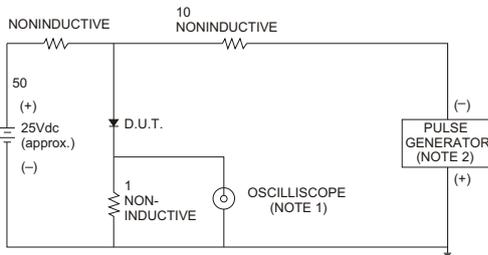
**FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE**



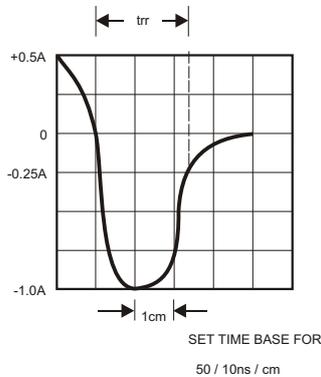
**FIG.2-TYPICAL FORWARD CHARACTERISTICS**



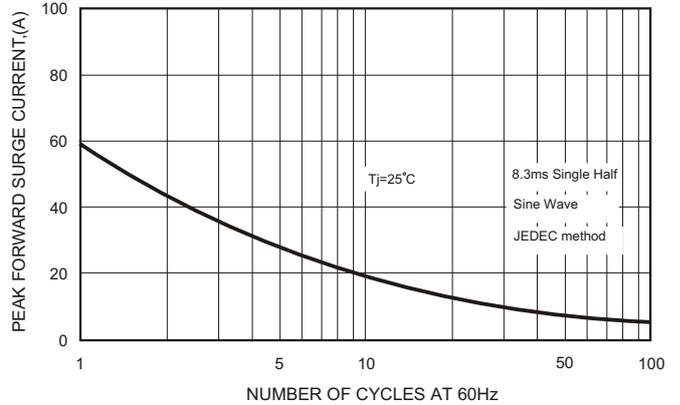
**FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS**



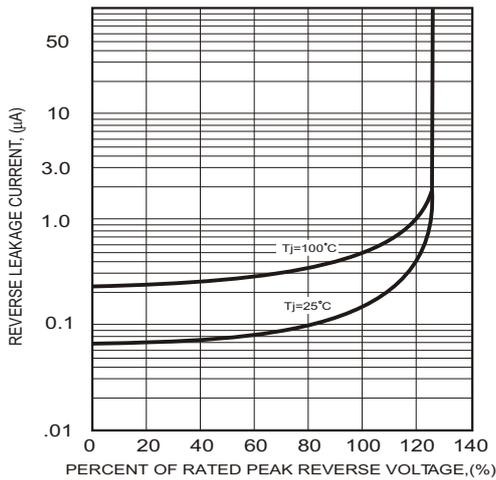
NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm.22pF.  
2. Rise Time= 10ns max., Source Impedance= 50 ohms.



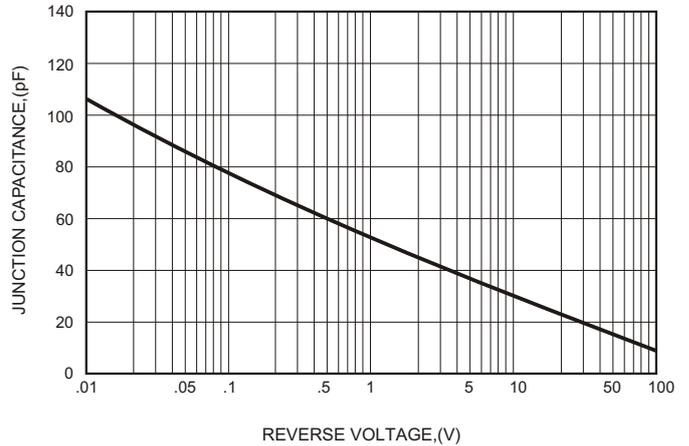
**FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT**



**FIG.5 - TYPICAL REVERSE CHARACTERISTICS**

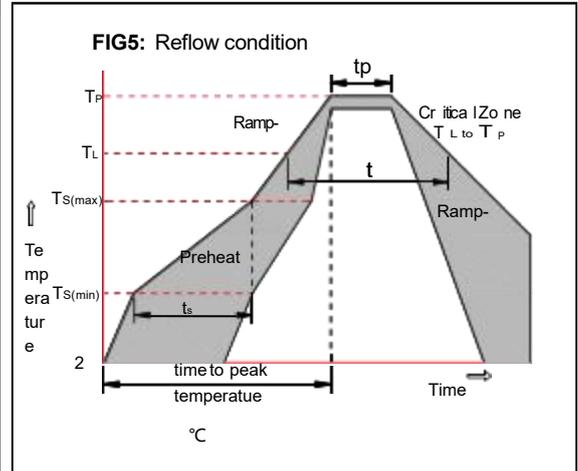


**FIG.6-TYPICAL JUNCTION CAPACITANCE**



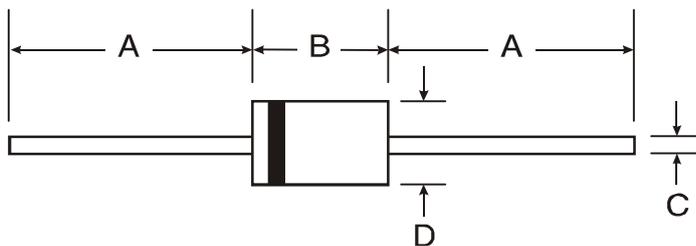
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150 °C
	-Temperature Max( $T_{s(max)}$ )	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3 °C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature( $T_L$ )(Liquid us)	+217 °C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_p$ )		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp ( $T_p$ )		8 min. Max
Do not exceed		+260 °C



Package Dimensions & Suggested Pad Layout

DO-15



DO-15		
Dim	Min	Max
A	25.40	-
B	5.80	7.60
C	0.70	0.90
D	2.60	3.60
All Dimensions in mm		